

### Technical Data Sheet

#### **MODEL NO: S110ANB4**

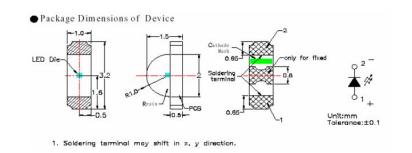
#### 1204Package 3.2\*1.5mm Chip LEDs

#### Features:

- Package in 8mm tape on 7" diameter reel
- Compatible with automatic placement equipment
- Compatible with reflow solder process

#### Applications:

- Indicators
- Automotive: backlighting in dashboard and switch
- Backlight for LCD



Dice material	Emitted color	Lens Color		
InGaN	Blue	Water Clear		

### Electrical/Optical Characteristics(Ta=25°C)

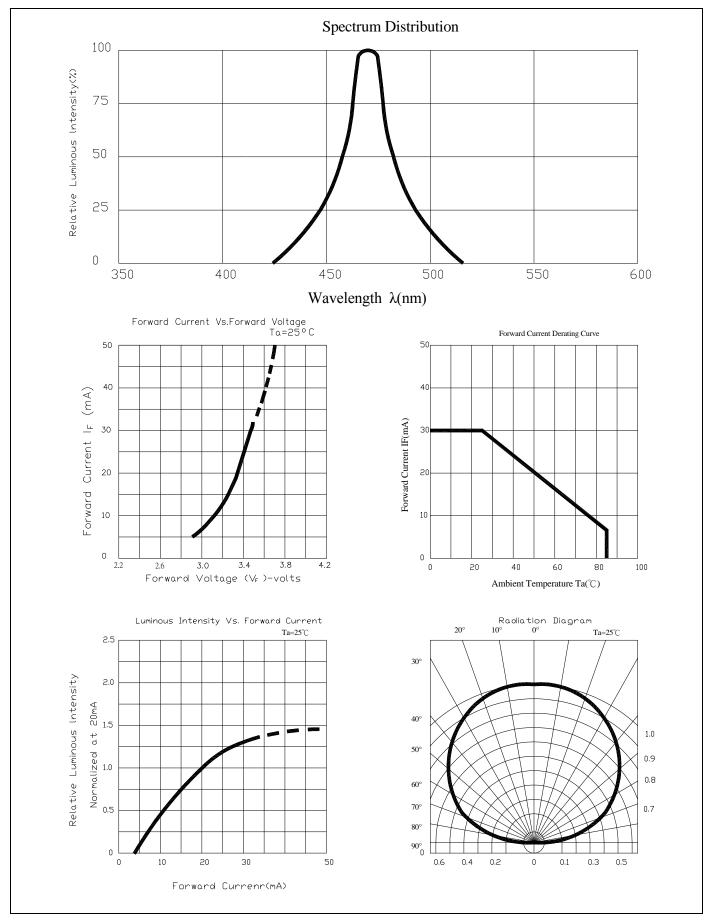
Parameter	Symbo1	Condition	Min	Тур.	Max	Unit
Luminous Internisity	Iv	IF=20mA	40	60		mcd
Dominant Wavelength	λD	IF=20mA		470		nm
Peak Emission Wavelength	λр	IF=20mA		465		nm
Viewing Angle	2 🖯 1 / 2	IF=20mA		140		Deg
Forward Voltage	VF	IF=20mA		3. 2	3.8	V
Reverse Current	IR	VR=5V			10	μA

#### Absolute Maximum Ratings(Ta=25℃)

Parameter	Symbol	Maximum	Unit
Power Dissipation	Pd	78	mW
Peak Forward Current(1/10 Duty Cycle 0.1ms Pulse Width)	IF(Peak)	100	mA
Continuous Forward Current	IF	30	mA
Reverse Voltage	VR	5	V
Derating Linear From 25℃		0.3	mA/°C
Operating Temperature Range	Topr	-30 to +80	$^{\circ}\! \mathbb{C}$
Storage Temperature Range	Tstg	-40 to +90	$^{\circ}\!\mathbb{C}$

#### 20090727

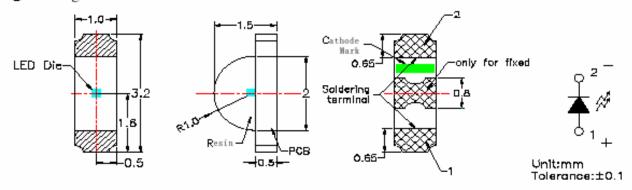




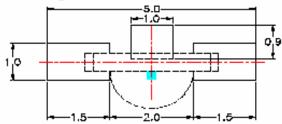


◆ Dimensions / Taping and Package Spec.





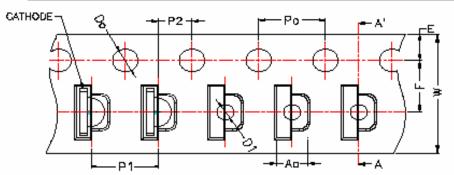
- 1. Soldering terminal may shift in x, y direction.
- Recommended Soldering Pad Dimensions

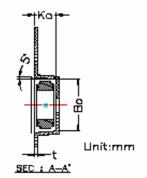


Unit:mm

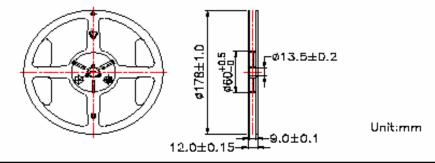
■ Tape Specification: 3000pcs Per Reel

	Packing Size												
Item	W	P1	Ε	F	Do	D1	Po	10Po	P2	Αo	80	Κσ	t
Spec.	B.00	4.00	1.75	3.50	1.5D	1.00	4.00	40.00	2.00	1.75	3.40	1.25	0.23
Tolerance	±0.20	±0.10	±0.10	±0.05	+0.10 -0.09	±0.05	±0.05	±0.20	±0.05	±0.10	±0.10	±0.10	±0.02

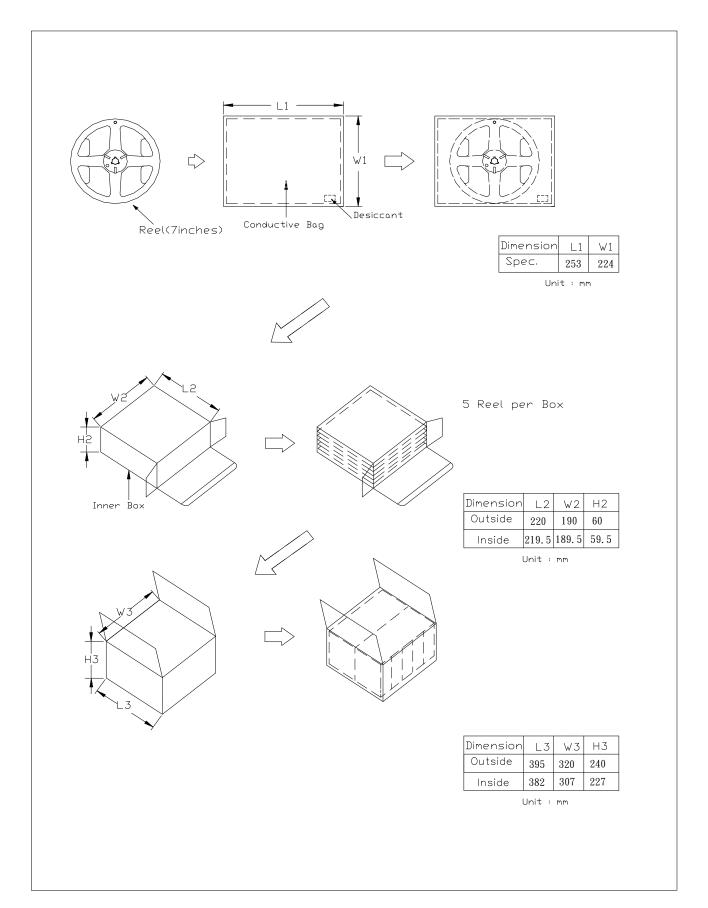




Package Dimensions of Reel :







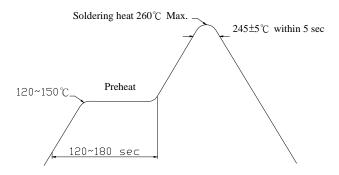


### Descriptions :

- The Chip-LED Taping is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature application, etc.

### Soldering heat reliability (DIP):

Please refer to the following figure:



#### Precautions For Use :

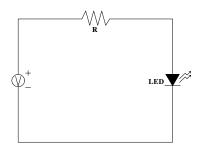
• Over – current – proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

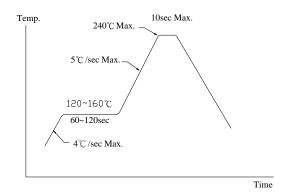
- Storage
- 1. The operation of temperature and R.H. are :  $5^{\circ}$ C  $\sim 30^{\circ}$ C, 60%R.H. Max..
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}\text{C}\pm5^{\circ}\text{C}$  for 15hrs.



### **●** Test Circuit



# Reflow Temp. / Time :



### Reliability Test Items And Conditions

The reliability of products shal be satisfied with items listed below.

No.	Items	Test Condition	Test Hours/Cycles	Sample Size
1	Solder Heat	TEMP : 260°C±5°C	5 sec	48 pcs
2	Temperature Cycle	90°C ~ 25°C ~ -30°C ~ 25°C 30m 5m 30m 5m	300Cycles	48 Pcs
3	Thermal Shick	100°C ~ -55°C 10m 10m	100Cycles	48 Pcs
4	Operation Life	If=20mA	1000 Hrs	48 Pcs
5	High Temperature Storage	Temp:90°C	1000Hrs	48 Pcs
6	Low Temperature Storage	Temp:-30°C	1000Hrs	48 Pcs
7	High Temperature/High Humidity	80°C / R.H80%	1000Hrs	48 Pcs